

FIG. 1.

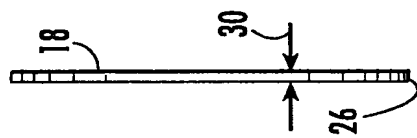


FIG. 3b.

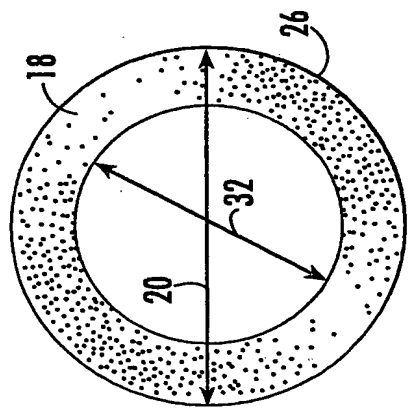


FIG. 3a.

```

graph TD
    START([START]) --> 80[MOUNT BLADE & WAFER]
    80 --> 82[WAFER DICING]
    82 --> 84{CUT < MAXIMUM CUTS}
    84 -- YES --> 96
    84 -- NO --> 86[HEIGHT SENSE BLADE EDGE]
    86 --> 88[CALCULATE EXPOSURE & SEPARATION DISTANCE]
    88 --> 90{FLANGE CLEARANCE > MINIMUM CLEARANCE}
    90 -- NO --> 94
    90 -- YES --> 92{DISTANCE < PRESELECTED DISTANCE}
    92 -- YES --> 96
    92 -- NO --> 94
    94[STOP SAW OPERATION]
    96 --> 80

```

FIG. 7.

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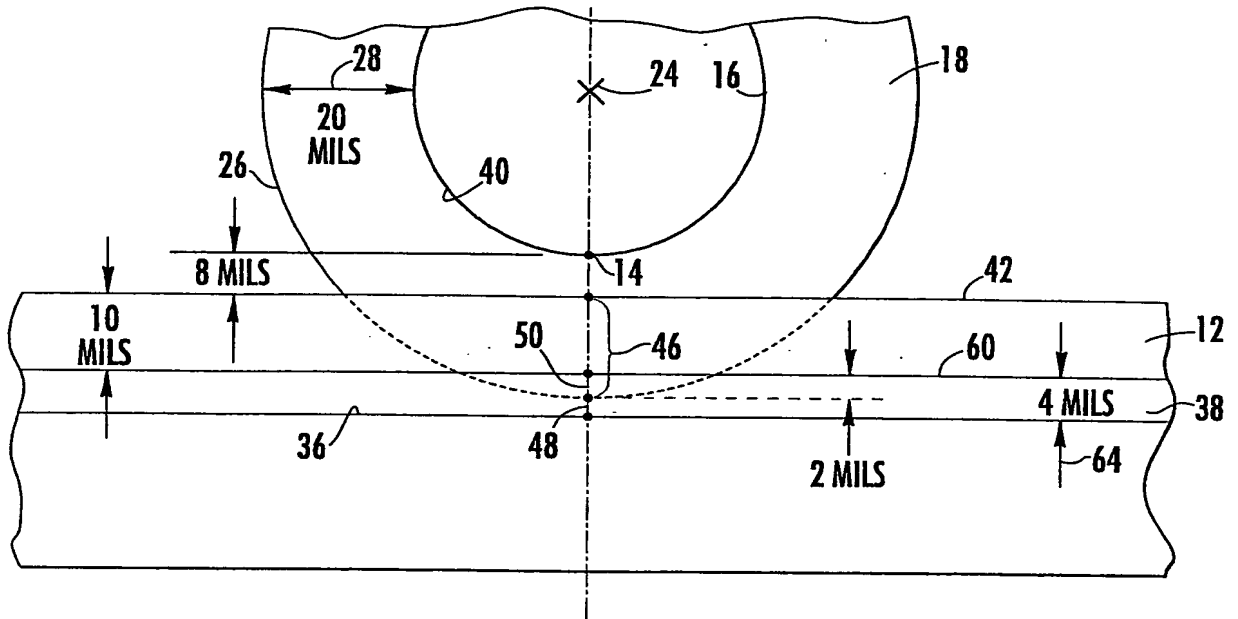


FIG. 4.

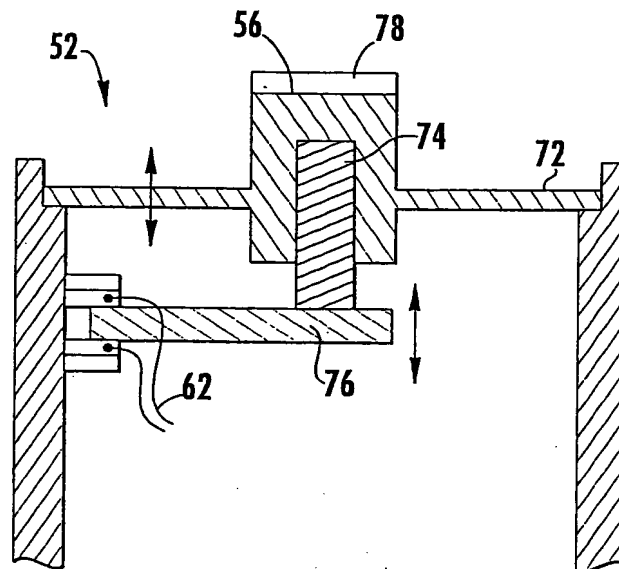


FIG. 6.

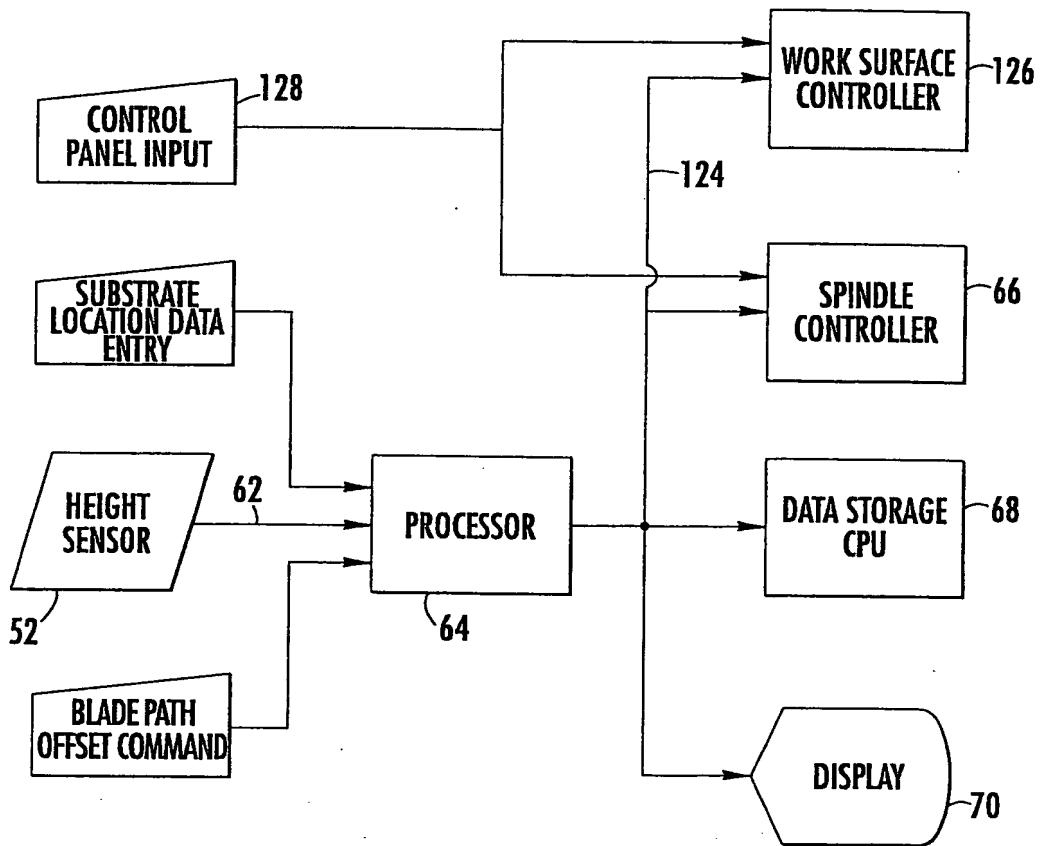
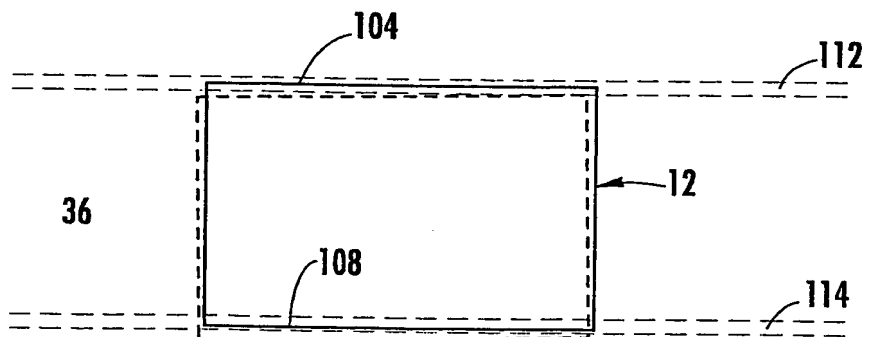
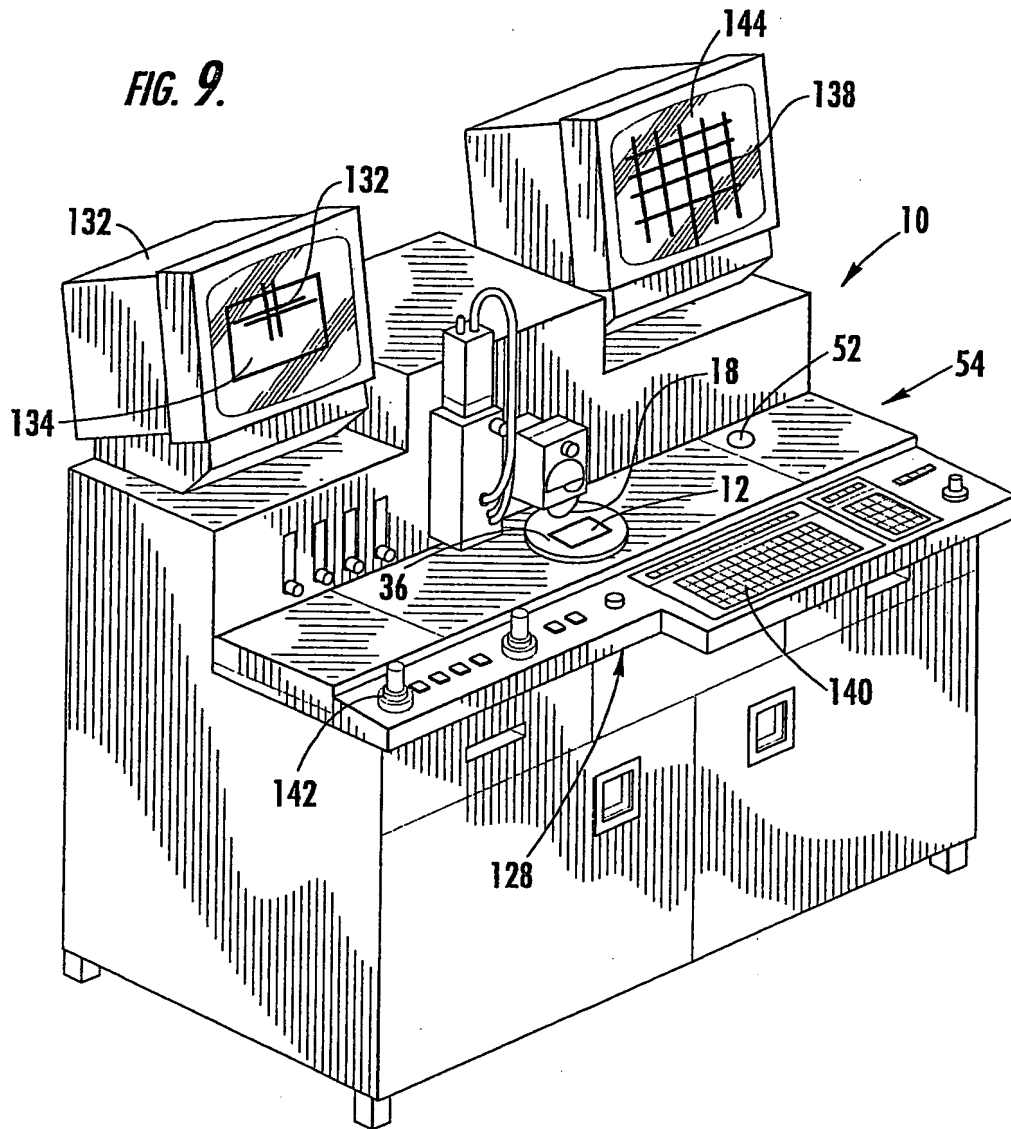
**FIG. 5.**

FIG. 8b.

FIG. 9.**FIG. 8c.**

